ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INCLUSTRES®	. Bannockb	urn. Illinois. A	ll rights reserved unitions.	under both	This docume level parts, t	ent is a declarat he declaration of	on of the suncompasse	ubstances s all lowe	within the man r level materials	ufacturer liste s for which th	d item. Note: e manufacture	if the item is an as er has engineering	ssembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distri				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					Materials and	als and Mfg Information			
Supplier Information														
Company name*			Company unique ID			Unique ID Authority					Response Date*			
onsemi								2024-	2024-04-20					
Contact Name	Title - Contact			Phone - Conta			et* Er			Emai	Email - Contact*			
Product-Env-Stewards Product Env			nviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repr			presentative			Phone - Representative*				Emai	Email - Representative*			
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Prod	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	]	Manufacturing Site		Weight*	UOM	Unit Type	
	NCP3020	CP302055MNTWG INT D		NT Driver and MOSFET		2024-04-20		]	MY5		73.67428	mg	Each	
Manufacturing Proccess Informatio	n					·								
Terminal Plating / Grid Array Mater	erminal Plating / Grid Array Material Terminal Base		Alloy	J-STD-020 MSL Rating		Peak Proc	Peak Process Body Temperatu		ure Max Time at Peak Temper		emperature Number of Reflow Cycles		cles	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260		С	30	sec	conds 3			
Comments														
evel 1 - maximum time at peak temperature	during sol	dering is 10-3	0 seconds											
for more information regarding material co	mposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.34295	mg	Supplier	Zinc (Zn)	7440-66-6		0.0076	mg
			Supplier	Iron (Fe)	7439-89-6		0.1522	mg
			Supplier	Copper (Cu)	7440-50-8		6.178	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0051	mg
Die	0.317142	mg	Supplier	Silicon (Si)	7440-21-3		0.3171	mg
Die Attach Solder	2.17762	mg	Supplier	Silver (Ag)	7440-22-4		0.0544	mg
			А	Lead (Pb)	7439-92-1	7a	2.0143	mg
			Supplier	Tin (Sn)	7440-31-5		0.1089	mg
Ероху	0.1291	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0103	mg
			Supplier	Bismaleimide	13676-54-5		0.0348	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		0.0116	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.0013	mg
			Supplier	PTFE	9002-84-0		0.071	mg
Lead Frame	31.0723	mg	Supplier	Silver (Ag)	7440-22-4		1.5538	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0373	mg
			Supplier	Iron (Fe)	7439-89-6		0.7458	mg
			Supplier	Copper (Cu)	7440-50-8		28.7106	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0249	mg
Mold Compound-Black	31.2746	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.0328	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1564	mg
			Supplier	Silica (SiO2)	14464-46-1		27.5216	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.5637	mg
Plating	2.10085	mg	Supplier	Tin (Sn)	7440-31-5		2.1009	mg
Wire Bond - Cu	0.259717	mg	Supplier	Palladium (Pd)	7440-05-3		0.0047	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.2548	mg